Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type* **Distribute**

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, Aug 09, 2014 03:21 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
GBPC3510	GBPC3510	GBPC_T			SUBCONTRACTOR	**18.194440**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Other	CU Alloy	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration	**Declaration Type * Custom**
RoHS Directive 2011/65/EU	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *	**4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions**	**Supplier Acceptance * Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

- 7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).
- 7(c)-I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Declaration Signature

Supplier Signature	David Lancaster DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name GBPC_T

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Aluminum Heat sink	Aluminum & its alloys	3345.000	Supplier		Aluminum	3345.000	7429-90-5	183847
Case	Other Organic Materials	4075.000	Supplier		Epoxy Resin	815.000	25068-38-6	44794
			Supplier		Phenolic resin	326.000	9003-35-4	17918
			Supplier		Phosphorus	81.500	7723-14-0	4479
			Supplier		Silica	2852.500	14464-46-1	156779
EPOXY	Other Organic Materials	6971.225	B	Antimony/Antimony Compounds	Antimony Trioxide	223.061	1309-64-4	12260
			Supplier		Carbon Black	55.765	1333-86-4	3065
			Supplier		Cycloaliphatic Anhydride	2510.000	19438-60-9	137954
			Supplier		Epoxy Resin	1394.133	2389-87-0	76624
			Supplier		Silica, vitreous	2788.266	60676-86-0	153248
GPP Dice	Ceramics / Glass	36.889	Supplier		Gold	0.055	7440-57-5	3
			A	Lead/Lead Compounds	Lead Bisilicate	3.394	65997-18-4	187
			B	Nickel (external applications only)	Nickel	0.240	7440-02-0	13
			Supplier		Silicon	33.200	7440-21-3	1825
Marking Ink	Other Organic Materials	2.000	Supplier		1-Butanol	0.100	71-36-3	5
			Supplier		2-Methyl-1-propanol	0.020	78-83-1	1
			Supplier		Aluminum	0.580	7429-90-5	32
			Supplier		Formaldehyde	0.020	50-00-0	1
			Supplier		Hexahydrophthalic anhydride	0.100	85-42-7	5
			Supplier		Tributyl phosphate	0.600	126-73-8	33
			Supplier		Triethyl Phosphate	0.580	78-40-0	32
Plating Layer	Aluminum & its alloys	1.966	B	Nickel (external applications only)	Nickel	1.966	7440-02-0	108
Solder Paste	Other Nonferrous metals & alloys	20.000	A	Lead/Lead Compounds	Lead	18.500	7439-92-1	1017
			Supplier		Silver	0.500	7440-22-4	27
			Supplier		Tin	1.000	7440-31-5	55
Solder Wafer	Other Nonferrous metals & alloys	85.360	A	Lead/Lead Compounds	Lead	78.958	7439-92-1	4340
			Supplier		Silver	2.134	7440-22-4	117
			Supplier		Tin	4.268	7440-31-5	235
Terminal (plating Cu)	Copper & its alloys	2516.000	Supplier		Copper	2511.899	7440-50-8	138059
			Supplier		Iron	3.019	7439-89-6	166
			Supplier		Phosphorus	1.082	7723-14-0	59
Thin Copper	Copper & its alloys	1141.000	Supplier		Copper	1139.859	7440-50-8	62649
			Supplier		Iron	0.913	7439-89-6	50
			Supplier		Phosphorus	0.228	7723-14-0	13